

VT-4BC

UL Approval: E214381 Version: 15/09/2023

Metal Base Laminate

General Information

- > Thermal conductivity -- 10 W/mK
- > Ceramic Filled
- > Halogen Free
- > Flammability UL94 V-0
- > MOT 155°C
- > High Tg 180°C
- > Suitable for High Temperature Applications

Application

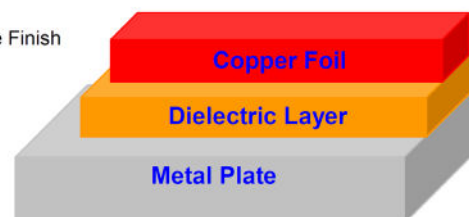
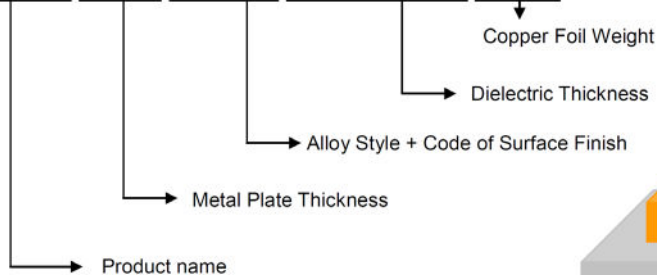
- > Super Bright Lighting
- > Power Modules (IGBT)
- > Controllers
- > Motor Drives
- > Rectifiers
- > Power Supply & Power Conversion

Storage Condition

		Laminate
Storage Condition	Temperature	Room
	Relative humidity	/

Designation of IMS Laminate

VT-4BC 1.0mm Al 5052A .004" Dielectric 3oz Cu



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Laminate Properties

Item	Test Method (IPC-TM-650) or as noted	Unit	Dielectric Thickness			
			100µm	125µm	150µm	
Thermal Conductivity	ISO 22007-2	W/mK	10			
Thermal Impedance	ISO 22007-2	°C*in ² /W	0.016	0.019	0.023	
Tg	DSC	2.4.25	°C			
Td	TGA	ASTM D3850	°C			
Thermal Stress	Solder Dip @ 288°C	2.4.13.1	Minute			
Hi-Pot Proof Test	DC	2.5.7.2	V	3000	4000	5000
Breakdown Voltage	AC	2.5.6.3	V	8000	9000	10000
Dk @ 1MHz	C-24 /23 / 50	2.5.5.3	-			
Df @ 1MHz	C-24/ 23 / 50	2.5.5.3	-			
Volume Resistance	After Moisture	2.5.17.1	MΩ-cm	5.0E+8		
	E-24/125			3.0E+7		
Surface Resistance	After Moisture	2.5.17.1	MΩ	2.0E+7		
	E-24/125			5.0E+6		
Peel strength (3oz)	As Received	2.4.8	Lb/in			
CTI	As Received	ASTM D3638	V			
Flammability	As Received	UL 94	Rating			
RTI	Electric	UL 746E	°C			
	Mechanical		°C			

- (1) All test data provided are typical values and not intended to be specification values.
- (2) Hi-Pot proof test (600VDC) is performed 100% on the whole working panels (with copper foil). Any higher requirement of Hi-Pot test can be AABUS.
- (3) Breakdown test is a destructive test, which is done on substrate (without copper foil) of a random sample in the FQC laboratory.

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Availability

Metal Plate Selection

Alloy Style		Thermal Conductivity (W/mK)	Hardness (HV)	Tensile Strength (MPa)	Density (g/cm ³)	CTE (ppm/°C)	Standard Thickness (mm)
Al	5052H32	138	68	215	2.7	23.8	1.0, 1.5, 2.0, 3.0
	6061T6	167	95	276	2.7	23.6	1.0, 1.5, 2.0
	CTE II	170	45	189	2.7	19.0	1.0, 1.5, 2.0
Cu	C1100	386	95	310	8.9	16.8	1.0, 1.5, 2.0

Remark: Additional thicknesses could be available upon request.

Laminate

Item	Availability	
Dielectric Thickness	0.004" (100µm), 0.005" (125µm), 0.006" (150µm)	
Standard Size	Imperial (inch)	18.11*24.02
	Metric (mm)	460*610
Copper Foil Weight	2oz, 3oz, 4oz, 5oz, 6oz, 9oz, 14oz	

Remark: Additional thicknesses could be available upon request.

Surface Finish for Al Plate

Code	Surface Finish
None	Default Brushing
"A"	Anodizing
"ER I"	High Emissivity

Protective Film for Copper Plate

Type	Material	Max Operation Temperature
Standard	PET	170 °C
High Temperature	Polyimide	270 °C